

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a first semiconductor chip provided with a first electrode on a first main surface and a second semiconductor chip provided with a second
5 electrode on a second main surface. The first and the second semiconductor chips are integrated so that the first and second main surfaces are opposed to one another and the first and second electrodes are electrically connected. The second semiconductor chip is polished from the opposite side of the
10 second main surface so that the second semiconductor chip has a thickness smaller than the thickness of the first semiconductor chip.